产品承认书 **PRODUCT SPECIFICATIONS**

Customer	(客户):	
Product	(物料名称):	XJ0.9TFT-13Pin
Driver (驱动):	ST7735S
Model (规格型号) : _	
Date	(日期): <u>2</u>	014-03-25

客户确认 Customer Approval					
项目负责人 Project Manager					
品质主管 Director of Quality					
采购工程师 Purchasing Engineer					

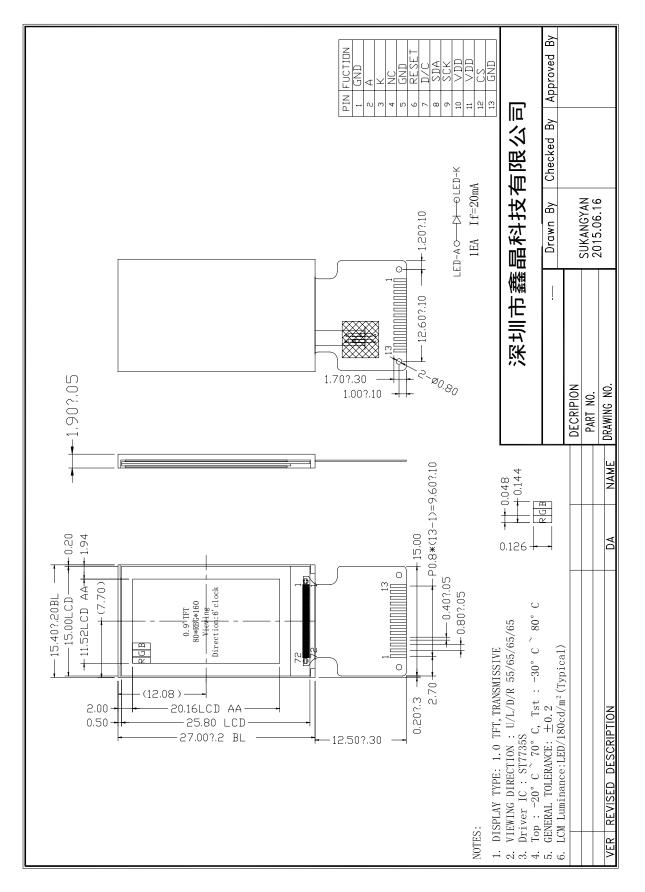
TEL: 袁小姐 15914134963 QQ:3222O57621 邮箱:lcd_xj@126.com 网址:http//www.lcdxj.com 阿里店铺:http://szxjlcd.1688.com

3. General Specifications

XJ0.9TFT-13PIN is a TFT-LCD module. It is composed of a TFT-LCD panel, driver IC, FPC, a back light unit. The $0.9^{\prime\prime}$ display area contains 80×160 pixels and can display up to 262K colors. This product accords with RoHS environmental criterion.

Item	Contents	Unit	Note
LCD Type	TFT	-	
Display color	262K		
Viewing Direction	6	O'Clock	
Gray scale inversion direction	12	O'Clock	
Operating temperature	-20~+70	°C	
Storage temperature	-30~+80	°C	
Module size	Refer to outline drawing	mm	
Active Area(W×H)	11.52X20.16	mm	
Number of Dots	80×160	dots	
Controller	ST7735S	-	
Power Supply Voltage	2.8	V	
Outline Dimensions	Refer to outline drawing	-	
Backlight	1-LEDs (white)	pcs	
Weight		g	
Interface	4-wire-SPI	-	

4. Outline Drawing



5. Absolute Maximum Ratings(Ta=25°C)

Item	Symbol	Min.	Max.	Unit	Note
Power Supply Voltage	V _{CC}	-0.3	3.3	V	
Logic Signal Input /Output Voltage	VIOVCC	-0.3	V _{CC} +0.5	V	1,2

5.1 Electrical Absolute Maximum Ratings.(Vss=0V ,Ta=25°C)

Notes:

- If the module is above these absolute maximum ratings. It may become permanently damaged.
 Using the module within the following electrical characteristic conditions are also exceeded, the module will malfunction and cause poor reliability.
- 2. V_{CC} >V_{SS} must be maintained.

5.2 Environmental Absolute Maximum Ratings.

Item	Stor	age	Operat	Note	
item	MIN.	MAX.	MIN.	MAX.	NOIC
Ambient Temperature	-30°C	3°08	-20°C	70°C	1,2
Humidity	-	-	-	-	3

1. The response time will become lower when operated at low temperature.

2. Background color changes slightly depending on ambient temperature.

The phenomenon is reversible.

3. Ta<=40°C:85%RH MAX.

Ta>=40°C:Absolute humidity must be lower than the humidity of 85%RH at 40°C.

6. Electrical Specifications and Instruction Code

Paramet	ter Symbol		Condition	Min	Тур	Max	Unit	Note
Power supply		VCC	Ta=25°C	2.6	2.8	3.0	V	
Input	'H'	V _{IH}	V _{CC} =2.8V	0.8V _{CC}	-	V _{CC}	V	
voltage 'L'		V _{IL}	V _{CC} =2.8V	0	-	0.2V _{CC}	V	
Current		I _{CC1}	Normal mode	-	1.8	2.5	mA	1
Consump	onsumption I _{CC2}		Sleep mode	-	0.03	0.1	mA	1

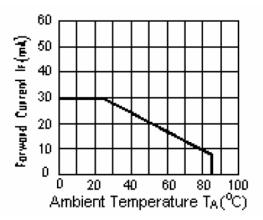
6.1 Electrical characteristics(Vss=0V ,Ta=25°C)

Note:

1: Tested in 1×1 chessboard pattern.

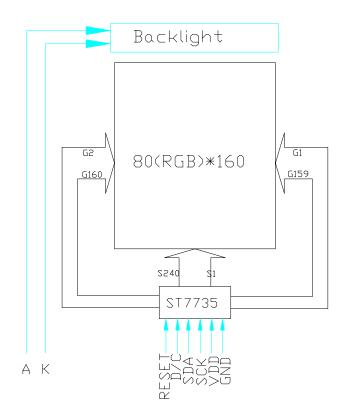
6.2 LED backlight specification(VSS=0V ,Ta=25°C)

Item	Symbol	Condition	Min	Тур	Max	Unit	Note
Supply voltage	Vf	lf=20mA	-	3.0	-	V	
Uniformity	∆Вр	lf=20mA	80	-		%	
Luminance for LCD	Lv	lf=20mA	-	180		Cd/m2	
Life for the LED	life	lf=20mA	-	30000	-	hours	



ILED VS TEMP

6.3 Block Diagram



6.4 SPI write/read to register or GRAM

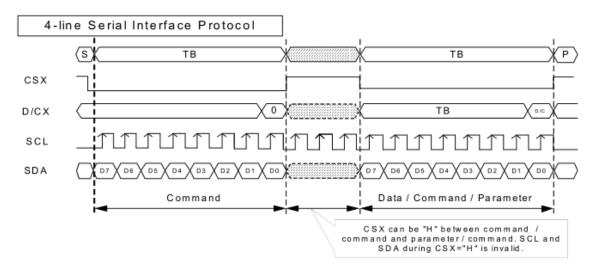


Figure6: 4-pins Serial Protocol for writing register or GRAM

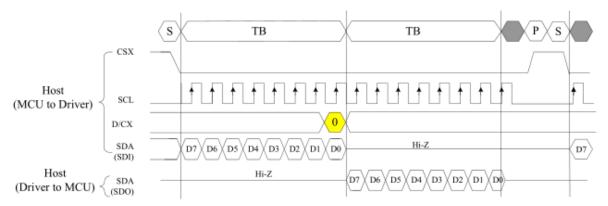
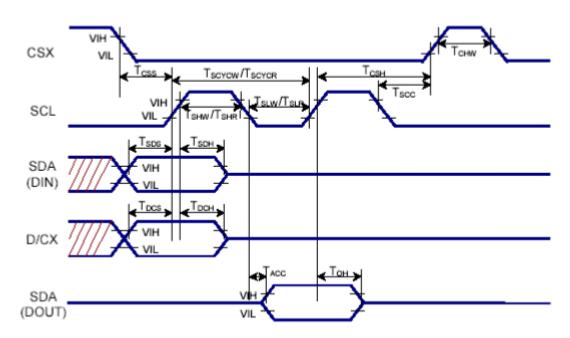


Figure6: 4-pins Serial Protocol (for DAH/DBH/DCH/0AH/0BH/0CH/0DH/0EH/0FH command: 8-bit read)



6.5 i80-System Interface Timing Characteristics

Table 17.3.2.2: 4 pin Serial Interface Characteristics

Signal	Symbol	Parameter	MIN	MAX	Unit	Description
	TCSS	Chip select setup time	10		ns	
CSX	TCSH	Chip select hold time	30		ns	
	TCHW	Chip select "H" pulse width	30		ns	
	TSCYCW	Serial clock cycle(Write)	66		ns	
	TSHW	S"L""H" pulse width(Write)	15		ns	
801	TSLW	S"L""L" pulse width(Write)	15		ns	
SCL	TSCYCR	Serial clock cycle(Read)	150		ns	
	TSHR	S"L""H" pulse width(Read)	60		ns	
	TSLR	S"L""L" pulse width(Read)	60		ns	
DICX	TDCS	D/CX setup time	5		ns	
D/CX	TDCH	D/CX hold time	5		ns	
	TSDS	Data setup time	5		ns	
SDA(DIN)	TSDH	Data hold time	5		ns	
(DOUT)	TACC	Access time	5	50	ns	For maximum CL = 30pF
	тон	Output disable time	10		ns	For minimum CL = 8pF

i80-System Bus Timing

6.6 Interface signals

Pin No.	Symbol	I/O	Function	
1	GND	Ρ	Ground.	
2	LEDA	Р	LED back light(Anode)	
3-4	LEDK1-LEDK2	Р	LED back light(Cathode)	
5	GND	Р	Ground.	
6	RESET	I	Reset the display	
7	D/C	I	Command/Data select	
8	SDA	I	Serial Input /output data bus	
9	SCK	I	Serial clock	
10-11	VCC	Р	Power supply	
12	CS	I	Chip select pin	
13	GND	Р	Ground.	

7. Optical Characteristics

Item	Symbol		Condition	Min.	Тур.	Max.	Unit	Note
Brightness	I	Зр	<i>θ</i> =0°	-	180	-	Cd/m ²	1
Uniformity	Z	1Вр	Ф =0°	80		-	%	1,2
	3	:00		-	65	-		
Viewing	6	:00	Cr≥10	-	65	-	Dee	0
Angle	9	:00	CI210	-	65	-	Deg	3
	12	2:00		-	55	-		
Contrast Ratio		Cr	<i>θ</i> =0°	300	500		-	4
Response	Tr		Φ=0°	-	10	-	ms	5
Time		T _f		-	10	-	ms	5
	W	х			0.28		-	
	vv	у			0.33		-	
	R	х			0.51		-	
Color of CIE	ĸ	у			0.34		-	
Coordinate	G	х	<i>θ</i> =0° Φ=0°		0.31		-	1,6
	G	У	Φ=0		0.56		-	
	В	х			0.15		-	
	D	у			0.14		-	
NTSC Ratio		S		50	60	-	%	

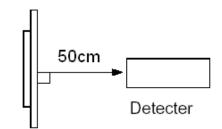
Note: The parameter is slightly changed by temperature, driving voltage and materiel

Note 1: The data are measured after LEDs are turned on for 5 minutes. LCM displays full white. The brightness is the average value of 9 measured spots. Measurement equipment PR-705 (Φ8mm)

Measuring condition:

- Measuring surroundings: Dark room.
- Measuring temperature: Ta=25°C.
- Adjust operating voltage to get optimum contrast at the center of the display.

Measured value at the center point of LCD panel after more than 5 minutes while backlight turning on.

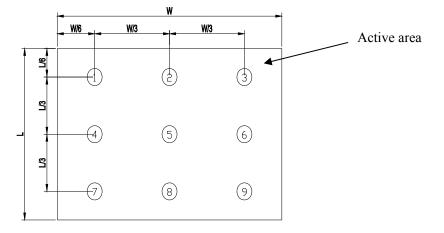


Note 2: The luminance uniformity is calculated by using following formula.

⊿Bp = Bp (Min.) / Bp (Max.)×100 (%)

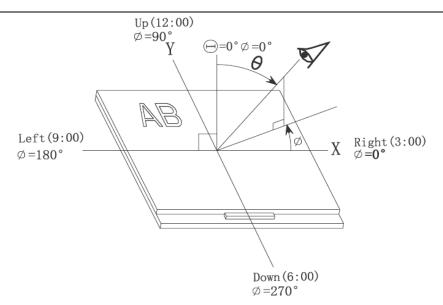
Bp (Max.) = Maximum brightness in 9 measured spots

Bp (Min.) = Minimum brightness in 9 measured spots.

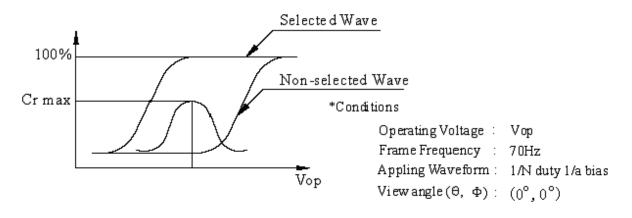


Note 3: The definition of viewing angle:

Refer to the graph below marked by heta and $m \phi$



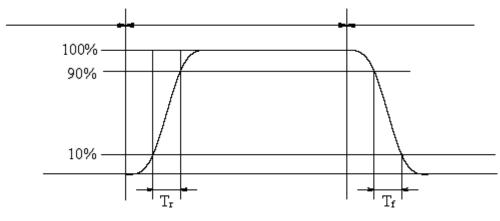
Note 4: Definition of contrast ratio.(Test LCD using DMS501)



Contrast ratio(Cr) = $\frac{Brightness \ of \ selected \ dots}{Brightness \ of \ non-selected \ dots}$

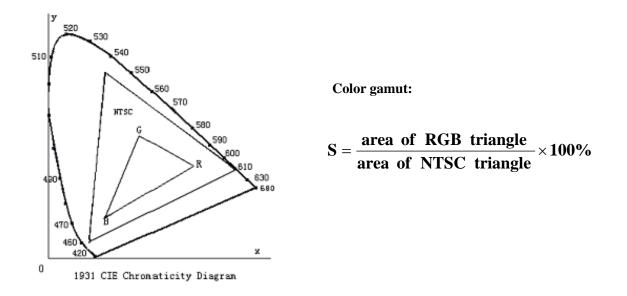
Note 5: Definition of Response time. (Test LCD using DMS501):

The output signals of photo detector are measured when the input signals are changed from "black" to "white"(falling time) and from "white" to "black"(rising time), respectively. The response time is defined as the time interval between the 10% and 90% of amplitudes.Refer to figure as below.



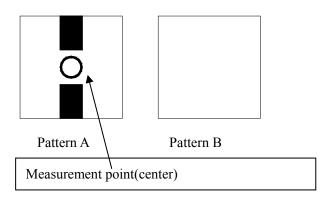
The definition of response time

Note 6: Definition of Color of CIE Coordinate and NTSC Ratio.



Note 7: Definition of cross talk.

Cross talk ratio(%)=|pattern A Brightness-pattern B Brightness|/pattern A Brightness*100



Electric volume value=3F+/-3Hex

8. Reliability Test Items and Criteria

No	Test Item	Test condition	Criterion
1	High Temperature Storage	80°C±2°C 96H Restore 2H at 25°C Power off	
2	Low Temperature Storage	-30°C±2°C 96H Restore 2H at 25°C Power off	A After testing
3	High Temperature Operation	70°C±2°C 96H Restore 2H at 25°C Power on	1. After testing, cosmetic and electrical defects should not
4	Low Temperature Operation	-20°C±2°C 96H Restore 4H at 25°C Power on	happen. 2. Total current consumption should not be more than twice
5	High Temperature/Humidity Operation	60°C±2°C 90%RH 96H Power on	of initial value.
6	Temperature Cycle	-30°C →80°C 30min 5min 30min after 5 cycle, Restore 2H at 25°C Power off	

Note: Operation: Supply 2.8V for logic system.

The inspection terms after reliability test, as below

	-
ITEM	Inspection
Contrast	CR>50%
IDD	IDD<200%
Brightness	Brightness>60%
Color Tone	Color Tone+/-0,05

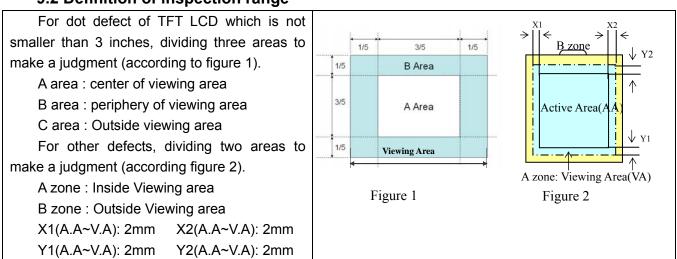
9 Quality level

9.1 Classification of defects

Major defects (MA): A major defect refers to a defect that may substantially degrade usability for product applications, including all functional defects(such as no display, abnormal display, open or missing segment, short circuit, missing component), outline dimension beyond the drawing, progressive defects and those affecting reliability.

Minor defects (MI): A minor defect refers to a defect which is not considered to be able to substantially degrade the product application or a defect that deviates from existing standards almost unrelated to the effective use of the product or its operation, such as black spot, white spot, bright spot, pinhole, black line, white line, contrast variation, glass defect, polarizer defect, etc.

9.2 Definition of inspection range



9.3 Inspection items and general notes

General notes	Should any defects which are not specified in this standard happen, additional standard shall be determined by mutual agreement between customer and our company. Viewing area should be the area which our company guarantees. Limit sample should be prior to this Inspection standard. Viewing judgment should be under static pattern. Inspection conditions Inspection distance: 250 mm (from the sample) Temperature : 25±5 °C Inspection angle : 45 degrees in 6 o'clock direction (all defects in viewing area should be inspected from this direction)		
Inspection items	Pinhole, Bright spot, Black spot, White spot, Black line, White Line, Foreign particle, Bubble	The color of a small area is different from the remainder. The phenomenon doesn't change with voltage	
	Contrast variation	The color of a small area is different from the remainder The phenomenon changes with voltage	
	Polarizer defect	Scratch, Dirt, Particle, Bubble on polarizer or betwee polarizer and glass	

Dot defect (TFT LCD)	The pixel appears bright or dark abnormally when display
Functional defect	No display, Abnormal display, Open or missing segment, Short circuit, False viewing direction
Glass defect	Glass crack, Shaved corner of glass, Surplus glass
PCB defect	Components assembly defect

9.4 Outgoing Inspection level

Outgoing Inspection	Inspection conditions	Inspection				
standard			Max.	Unit	L	AQL
Major Defects See 9.3 general notes		See 9.5		Ξ	0.65	
Minor Defects See 9.3 general notes		S	See 9.8	5	=	0.65
Note: Sampling standard conforms to GB2828						

9.5 Inspection Items and Criteria

		Judgment standard					
Inspection items				Category	Acceptable number		
				Calegory	A zone	B zone	
		b b	А	Ф<=0.10	Neglected		
	Black spot, White spot,		В	0.10<Ф<=0.2	1		
1	Pinhole, Foreign Particle, Particle	a	С	0.2<Ф	0	Neglected	
	in or on glass, Scratch on glass	h or on glass, cratch on glass $\Phi=(a+b)/2(m)$	D	-	-	_	
				tal defective point(B,C)	1		
		X		W<=0.02	Neglected		
	Black line, White	ine, and Particle Between Polarizer and	В	0.02 <w<=0.03 L<=1.0</w<=0.03 	1		
2	Between Polarizer and		С	0.03 <w<=0.05 L>1.0</w<=0.05 	0	Neglected	
	glass, Scratch on glass		D	0.05 <w, 1.0<l<="" td=""><td>0</td><td></td></w,>	0		
				tal defective point(B,C)	1		
3	Bright spot			any size	none	none	

			А	Ф<0.2	Neglected		
			В	0.2<Ф<=0.3	2	Neglecte	
4	Contrast variation		С	0.3<Ф<=0.4	1	d	
	Variation	$\Phi = (a+b)/2(mm)$		0.4<Ф	0		
			То	tal defective point(B,C)	3		
5	Bubble inside cell			any size	none	none	
	Polarizer defect	Scratch ,damage on polarizer, Particle on polarizer or between polarizer and glass.	Refer to item 1 and item 2.				
6	(if Polarizer is used)	Bubble, dent and convex	A	Ф<=0.1	Neglected		
			В	0.1 <Ф<=0.2	1	- Neglecte d	
			С	0.2 <Ф	0		
		Stage surplus glass					
		> 	B<=0.3mm				
7	Surplus glass	Surrounding surplus glass	Should not influence outline dimension and assemblin				
8	Open segment or o	open common	Not permitted				
9	Short circuit		Not permitted				
10	False viewing direction			Not permitted			
11	Contrast ratio uneven		According to the limit specimen				
12	2 Crosstalk			According to the limit specimen			
13	Black /White spot(display)			Refer to item 1			
14	Black /White line(display)			Refer to item 2			

Inspection items	Judgment standard
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			Category(application: B zone)	Acceptable number
	i) The front of lead terminals	A	a≤ t, b≤1/5W, c≤3mm	number
	w t a c	В	Crack at two sides of lead terminals should not cover patterns and alignment mark	
Glass	ii) Surrounding crack-non-contact side	b <	Inner borderline of the seal	Max.3
defect crack	iii) Surrounding crack- contact side seal c b a <u>c b a</u> <u>Inner border line of the seal</u> <u>Outer border line of the seal</u>	b <		defects allowed
	iv)Corner	А	a <= t, b <= 3.0, c <= 3.0	
	w b c	В	Glass crack should not cover patterns u and alignment mark and patterns.	
	defect	Glass defect crack Glass w b c c b c c b c c b c c b c c b c c b c c b c c b c c b c c c b c c c b c c c b c c c b c c c b c c c b c c c b c c c b c c c c c c c b c	Glass defect crack ii) Surrounding crack-non-contact side <u>seal</u> <u>liner border line of the seal</u> <u>outer border line of the seal</u> <u>liner border line of the seal</u> <u>b < brack</u> <u>b < brack}</u> <u>b < brack <u>b < brack</u> <u>b < brack</u> <u>b < brack}</u> <u>b < brack}</u> <u>b < brack}</u> <u>b < brack}</u> <u>b < brack} <u>b < brack}</u></u></u>	Glass Image: box of the seal of

Inspection items	Judgment standard
	Category(application: B zone)

		Component soldering: No cold soldering, short, open circuit, burr, tin ball The flat encapsulation component position deviation must be less than 1/3 width of the pin (Pic.1); the sheet component deviation: Pin deviates from the pad and contact with the near components is not permitted (Pic.2) lead defect: The lead lack must be less than 1/3 of its width; The lead burr must be less than 1/3 of the seam; Impurities connect with the near leads is not permitted	Component U L < W/2 W Component Soldering pad Lead L2>0 L2>0 L2>0
16	PCB defect	Connector soldering: Soldering tin is at contact position of the plug and socket is not permitted No foundation is scald Serious cave distortion on plug and socket contact pin is not permitted	bead Base Board Soldering tin is not permit in this area Soldering tin is not permit in this area
		Glue on root of the speaker receiver and motor lead: The insulative coat of the lead must join into the PCB; the protected glue must envelop to the insulative coat.	Glue Lead PCB Insulative coat

10. Precautions for Use of LCD Modules

10.1 Handling Precautions

- 10.1.1 The display panel is made of glass. Do not subject it to a mechanical shock by dropping it from a high place, etc.
- 10.1.2 If the display panel is damaged and the liquid crystal substance inside it leaks out, be sure not to get any in your mouth, if the substance comes into contact with your skin or clothes, promptly wash it off using soap and water.
- 10.1.3 Do not apply excessive force to the display surface or the adjoining areas since this may cause the color tone to vary.
- 10.1.4 The polarizer covering the display surface of the LCD module is soft and easily scratched. Handle this polarizer carefully.
- 10.1.5 If the display surface is contaminated, breathe on the surface and gently wipe it with a soft dry cloth. If still not completely clear, moisten cloth with one of the following solvents:
 - Isopropyl alcohol
 - Ethyl alcohol
 - Solvents other than those mentioned above may damage the polarizer. Especially, do not use the following:
 - Water
 - Ketone
 - Aromatic solvents
- 10.1.6 Do not attempt to disassemble the LCD Module.
- 10.1.7 If the logic circuit power is off, do not apply the input signals.
- 10.1.8 To prevent destruction of the elements by static electricity, be careful to maintain an optimum work environment.
 - a. Be sure to ground the body when handling the LCD Modules.
 - b. Tools required for assembly, such as soldering irons, must be properly ground.
 - c. To reduce the amount of static electricity generated, do not conduct assembly and other work under dry conditions.

d. The LCD Module is coated with a film to protect the display surface. Be care when peeling off this protective film since static electricity may be generated.

10.2 Storage precautions

- 10.2.1 When storing the LCD modules, avoid exposure to direct sunlight or to the light of fluorescent lamps.
- 10.2.2 The LCD modules should be stored under the storage temperature range. If the LCD modules will be stored for a long time, the recommend condition is:

Temperature :0°C $\sim 40°C$ Relatively humidity: $\leq 80\%$

- 10.2.3 The LCD modules should be stored in the room without acid, alkali and harmful gas.
- 10.3 The LCD modules should be no falling and violent shocking during transportation, and also should avoid excessive press, water, damp and sunshine.